PCN N	umber:	20161209	00	2	PCN	Dat	te:	Dec. 14, 2	016	
Title: Datasheet for L										
Customer Contact: PCN Manage						Dept:		Quality Ser	vices	
Change Type:										
	Assembly Site			Design			Wafe	r Bump Site		
	Assembly Process			Data Sheet		H		Wafer Bump Material		
	Assembly Materials		\square				Wafer Bump Process			
Mechanical Specification		\exists				Wafer Fab Site				
Packing/Shipping/Labeling			Test Process			Wafer Fab Materials		s		
					П		r Fab Process	0		
Notification Details										
Description of Change:										
Texas Instruments Incorporated is announcing an information only notification etc.										
					•, .					
The pro	oduct datasheet(s)	is being upd	ate	d as summarized belo	w.					
		2 .								
The fol	lowing change hist	ory provides	fur	ther details.						
bin -										
- 🔫 i	ÈXAS NSTRUMENTS						LP	3875-ADJ		
				SNVS247E-S	EPTEMB	ER 2003	-REVISED	AUGUST 2016		
Change	es from Revision D (April 2	2013) to Revision	E					Page		
• Add	led Device Information table	, Pin Configuration	n and	Functions section, ESD Ratings	s and Th	nermal	Informatio	on		
tabl	es, Feature Description sect	tion, Device Functi	onal	Modes, Application and Implem	entation	sectio	n, Power			
Sup	pply Recommendations sections sections sections and Orderable Informations	on, Layout section	, De	vice and Documentation Suppor	t section	i, and <i>l</i>	Mechanic	al, 1		
	Packaging, and Orderable Information section									
Deleted all Information re: 10-220 package, which is obsolete. Changed all VIN and VOUT pin names to IN and OUT in drawings and text										
Changed all VIN and VOOT pin names to IN and OOT in drawings and text										
Cha	anged Changed R _{eua} values:	SOT-223 package	e fror	n "90°C/W" to "65.2°C/W, DDPA	К/ТО-2	63 pac	kage fron	n		
"60°	°C/W" to "40.3°C/W"							4		
				-of-date information; added Pow						
Jun	ction Temperature							12		
The de			_							
	tasheet number wi	li be changin	_					hange Ter		
	e Family			Change From:				hange To:		
LP387	'5-ADJ			SNVS247D			3	NVS247E		
				atasheet links provide	ed.					
http://	www.ti.com/produc	<u>ct/LP3875-Al</u>	<u>)</u>							
_										
	n for Change:									
To mor	e accurately reflect	t device char	act	eristics.						
Antici	pated impact on I	Fit, Form, F	une	ction, Quality or Rel	iabili	ity (positi	ve / negativ	e):	
No anticipated impact. This is a specification change announcement only. There are no changes to										
the actual device.										
Changes to product identification resulting from this PCN:										
None.										

Product Affected:										
LP3875EMP-ADJ/NOPB	LP3875EMPX-ADJ/NOPB	LP3875ES-ADJ	LP3875ES-ADJ/NOPB							
LP3875ESX-ADJ/NOPB										

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com